



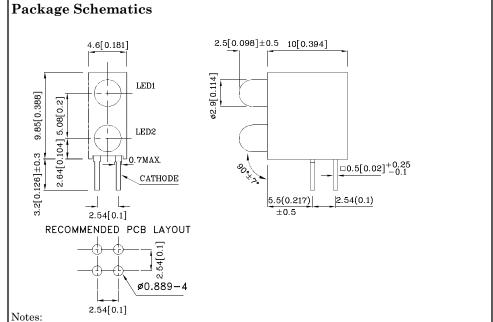
### **Features**

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- $\bullet$  Reliable & robust
- Custom color combinations available
- RoHS Compliant

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- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		UG (GaP)	Unit	
Reverse Voltage	$V_{\mathrm{R}}$	5	V	
Forward Current	$I_{\mathrm{F}}$	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA	
Power Dissipation	$P_{D}$	62.5	mW	
Operating Temperature	T <sub>A</sub> -40 ~ +85		°C	
Storage Temperature	Tstg	-40 ~ +8 <b>5</b>	C	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds			
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds			

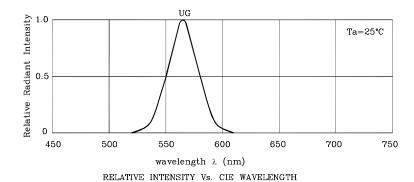
Operating Characteristics ( $T_A$ =25°C)		UG (GaP)	Unit
Forward Voltage (Typ.) $(I_F=10 \text{mA})$	$V_{\mathrm{F}}$	2	V
Forward Voltage (Max.) $(I_F=10 \text{mA})$	$V_{\mathrm{F}}$	2.5	V
Reverse Current (Max.) $(V_R=5V)$	$I_R$	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) $(I_F=10\text{mA})$	λР	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) $(I_F=10\text{mA})$	λD	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	$\triangle \lambda$	30	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	15	pF

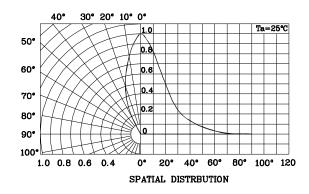
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} Luminous \ Intensity \\ CIE127\text{-}2007* \\ (I_F\text{=}10\text{mA}) \\ mcd \end{array}$		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XQT2LUG11D	Green	GaP	Green Diffused	10*	24*	565*	40°

<sup>\*</sup>Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

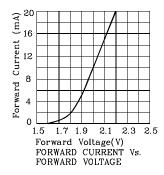


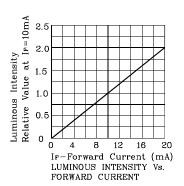


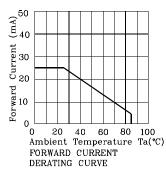


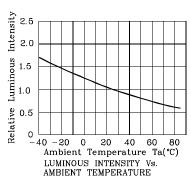


### **♦** UG

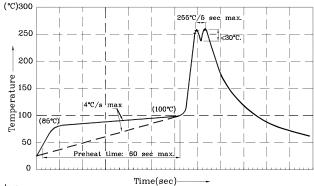








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

Notes. I. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of  $260^{\circ}C$  2. Peak wave soldering temperature between  $245^{\circ}C \sim 255^{\circ}C$  for 3 sec

(5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above  $85\,^\circ\text{C}.$  4.Fixtures should not incur stress on the component when mounting and

during soldering process. 5.SAC 305 solder alloy is recommended.

6. No more than one wave soldering pass

#### Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous Intensity / Luminous Flux: +/-15%

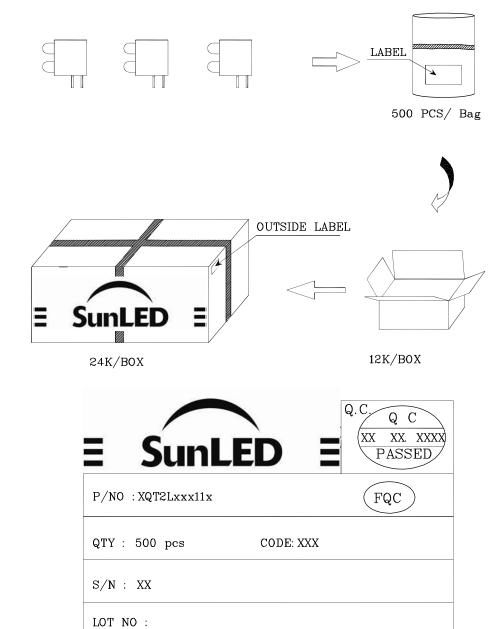
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.





## PACKING & LABEL SPECIFICATIONS



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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
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- 6. Additional technical notes are available at <a href="http://www.SunLEDusa.com/TechnicalNotes.asp">http://www.SunLEDusa.com/TechnicalNotes.asp</a>

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